

## WP57GYW

T-1 3/4 (5mm) Bi-Color Indicator Lamp



## DESCRIPTIONS

- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode

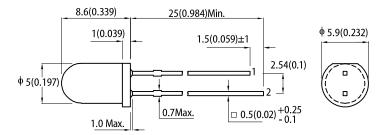
## **FEATURES**

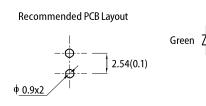
- Low power consumption
- · Long life solid state reliability
- RoHS compliant

## **APPLICATIONS**

- Status indicator
- Illuminator
- Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting

## **PACKAGE DIMENSIONS**





Notes

1. All dimensions are in millimeters (inches)

An onmersions are in minimiters (incres).
 Tolerance is 40.25(0.01") unless otherwise noted.
 Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

## **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA <sup>[2]</sup>		Viewing Angle <sup>[1]</sup>
			Min.	Тур.	201/2
WP57GYW	Green (GaP)	White Diffused	12	30	30°
	Yellow (CaAsP/GaP)		4	10	

Notes

- 41/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  2. Luminous intensity / luminous flux: +/-15%.
  3. Luminous intensity value is traceable to CIE127-2007 standards.

Yellow

## ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Farameter			Тур.	Max.	Unit
Wavelength at Peak Emission $I_F$ = 20mA	$\lambda_{peak}$	Green Yellow	565 590		nm
Dominant Wavelength I <sub>F</sub> = 20mA	$\lambda_{dom}$ <sup>[1]</sup>	Green Yellow	568 588		nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 20mA	Δλ	Green Yellow	30 35		nm
Capacitance	С	Green Yellow	15 20		pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Green Yellow	2.2 2.1	2.5 2.5	V

Notes:

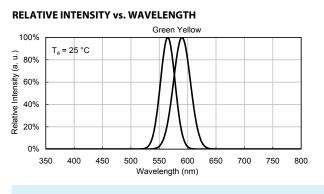
The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

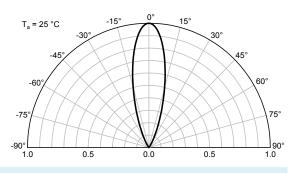
Provincia	Symbol	Valu		
Parameter		Green	Yellow	Unit
Power Dissipation	P <sub>D</sub>	62.5	75	mW
Junction Temperature	Tj	110 110		°C
Operating Temperature	T <sub>op</sub>	-40 to +85		°C
Storage Temperature	T <sub>stg</sub>	-40 to +85		°C
DC Forward Current	I <sub>F</sub>	25	30	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	140	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	8000	v
Lead Solder Temperature <sup>[2]</sup>	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base. 3. 5mm below package base. 4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

## **TECHNICAL DATA**



#### SPATIAL DISTRIBUTION



2.5

2.0

1.0

0.5

0.0

2.5

Luminous intensity normalised

100

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at T<sub>a</sub> = 25 ° 1.5

GREEN

50

40

30

20

10

0

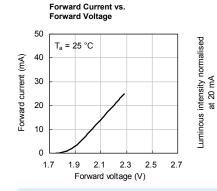
-40

-20 0

Permissible forward current (mA)



Luminous Intensity vs. Ambient Temperature



Forward Current vs.



50



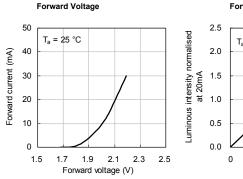
Ambient temperature (°C)

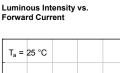
Luminous Intensity vs.

-40 -20 0 20 40 60 80

Ambient temperature (°C)

100





20 30 40

Forward current (mA)

10

20

Forward current (mA)

30 40 50

Luminous Intensity vs. Forward Current

T<sub>a</sub> = 25 °C

2.5

2.0

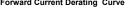
1.5

1.0

0.5

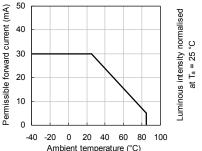
0.0

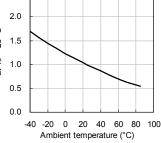
0 10



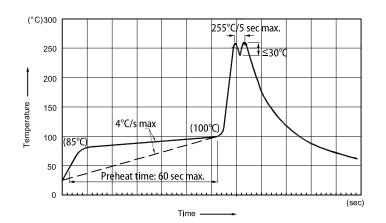
20 40 60 80

Ambient Temperature





#### **RECOMMENDED WAVE SOLDERING PROFILE**

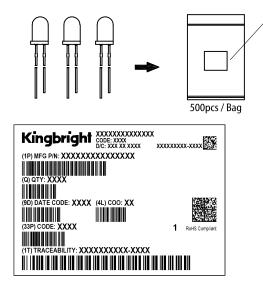


#### Notes:

- 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

- Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
  Do not apply stress to the epoxy resin while the temperature is above 85°C.
  Fixtures should not incur stress on the component when mounting and during soldering process.
- 5. SAC 305 solder alloy is recommended.
  6. No more than one wave soldering pass

### RACOMMEDICAL ABAELS OF DE ON TO CAROFICINS







## PRECAUTIONS

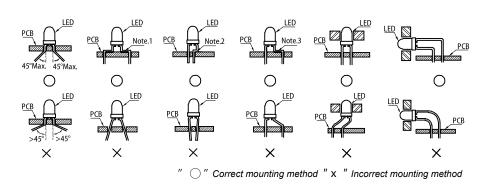
### **Storage conditions**

- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- 2. LEDs should be stored with temperature  $\leq$  30°C and relative humidity < 60%.
- Product in the original sealed package is recommended to be assembled within 72 hours of opening.
  Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

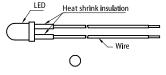
Label

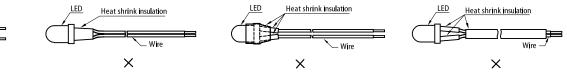
## **LED Mounting Method**

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.



2. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure.



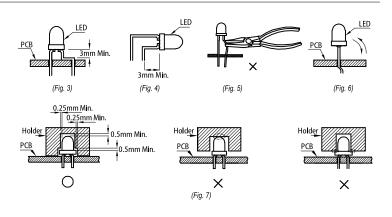


- PCB Stand-off Fig. 2)
- 3. Use stand-offs (Fig.1) or spacers (Fig.2) to securely position the LED above the PCB.
  - 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend (*Fig. 3 , Fig. 4*).
  - 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (*Fig. 5*)

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### **Lead Forming Procedures**

- 1. Do not bend the leads more than twice. (Fig. 6)
- 2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering. (Fig. 7)
- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through-hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



#### **PRECAUTIONARY NOTES**

- 1. 2.
- The information included in this document reflects representative usage scenarios and is intended for technical reference only. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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